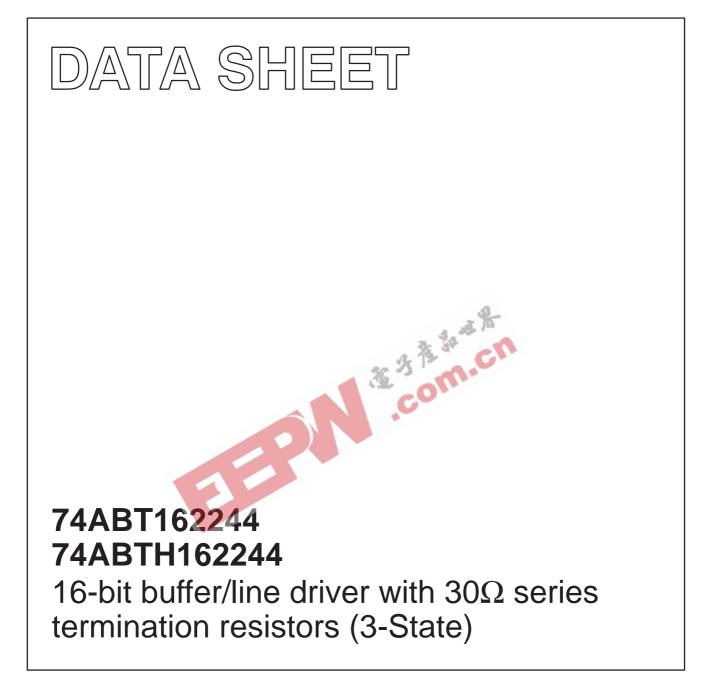
## INTEGRATED CIRCUITS



Product specification Supersedes data of 1998 Feb 25 IC23 Data Handbook 1998 Oct 22



## 16-bit buffer/line driver with $30\Omega$ series termination resistors (3-State)

## 74ABT162244 74ABTH162244

#### FEATURES

- 16-bit bus interface
- Multiple V<sub>CC</sub> and GND pins minimize switching noise
- Power-up 3-State
- 3-State buffers
- Output capability: +12 mA/-32mA
- Live insertion/extraction permitted
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Same part as 74ABT162244-1
- 74ABTH162244 incorporates bus hold data inputs which eliminate the need for external pull–up resistors to hold unused inputs
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

#### DESCRIPTION

The 74ABT162244 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed.

The 74ABT162244 device is a 16-bit buffer that is ideal for driving bus lines. The device features four Output Enables ( $1\overline{OE}$ ,  $2\overline{OE}$ ,  $3\overline{OE}$ ,  $4\overline{OE}$ ), each controlling four of the 3-State outputs.

The 74ABT162244 is designed with  $30\Omega$  series resistance in both the upper and lower output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

The 74ABT162244 is the same as the 74ABT16244-1. The part number has been changed to reflect industry standards.

Two options are available, 74ABT162244 which does not have the bus hold feature and the 74ABTH162244 which incorporates the bus hold feature.

#### 1OE 48 2OE 1 2 47 1A0 1Y0 3 46 1Y1 1A1 GND 4 45 GND 1Y2 5 44 1A2 6 43 1A3 1Y3 42 7 VCC VCC 2Y0 8 41 2A0 40 2Y1 9 2A1 10 39 GND GND 38 2Y2 1' 2A2 37 2Y3 12 2A3 3Y0 36 3A0 35 3Y1 3A1 14 GND 34 1 GND 3Y2 33 3A2 3Y4 1 32 3A3 31 VCC V<sub>CC</sub> 30 4Y0 19 4A0 4Y1 20 29 4A1 28 GND 21 GND 22 27 4Y2 4A2 26 4Y3 23 4A3 40E 24 25 3OE SA00013

**PIN CONFIGURATION** 

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS T <sub>amb</sub> = 25°C; GND = 0V	TYPICAL	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nAx to nYx	$C_{L} = 50 pF; V_{CC} = 5V$	1.8 3.2	ns
C <sub>IN</sub>	Input capacitance	$V_{I} = 0V \text{ or } V_{CC}$	3	pF
C <sub>OUT</sub>	Output capacitance	$V_{O} = 0V \text{ or } V_{CC}$ ; 3-State	7	pF
I <sub>CCZ</sub>	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5V$	500	μΑ
I <sub>CCL</sub>		Outputs Low; $V_{CC} = 5.5V$	10	mA

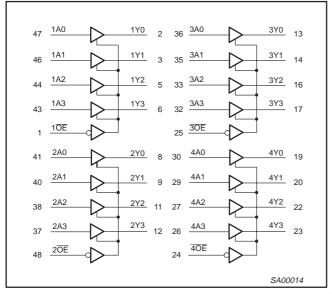
#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT162244 DL	BT162244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT162244 DGG	BT162244 DGG	SOT362-1
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH162244 DL	BH162244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH162244 DGG	BH162244 DGG	SOT362-1

## 16-bit buffer/line driver with $30\Omega$ series termination resistors (3-State)

## 74ABT162244 74ABTH162244

## LOGIC SYMBOL



### **FUNCTION TABLE**

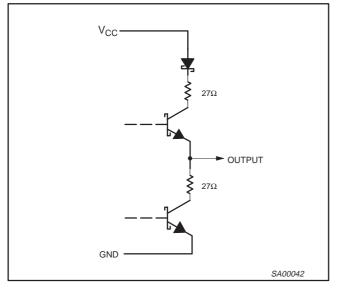
INPU	OUTPUTS	
nOE	nAx	nYx
L	L	
L	Н	Н
н	x	Z
H = High voltage level		

= Low voltage level L

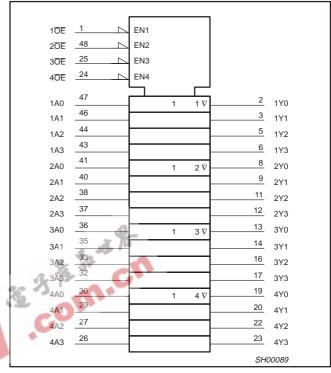
= Don't care

X Z = High impedance "off" state

### SCHEMATIC OF Y OUTPUTS



## LOGIC SYMBOL (IEEE/IEC)



### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
47, 46, 44, 43 41, 40, 38, 37 36, 35, 33, 32 30, 29, 27, 26	1A0 – 1A3, 2A0 – 2A3, 3A0 – 3A3, 4A0 – 4A3	Data inputs
2, 3, 5, 6 8, 9, 11, 12 13, 14, 16, 17 19, 20, 22, 23	1Y0 – 1Y3, 2Y0 – 2Y3, 3Y0 – 3Y3, 4Y0 – 4Y3	Data outputs
1, 48 25, 24	1 <u>0E,</u> 2 <u>0E,</u> 30E, 40E	Output enables
4, 10, 15, 21 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V <sub>CC</sub>	Positive supply voltage

## 16-bit buffer/line driver with $30\Omega$ series termination resistors (3-State)

## 74ABT162244 74ABTH162244

### **ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>**

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>1</sub> < 0	-18	mA
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	output in Low state	128	
		output in High state	-64	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIM	LIMITS	
		Min	Max	UNIT
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
VIL	Low-level input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
Tamb	Operating free-air temperature range	-40	+85	°C

## 16-bit buffer/line driver with $30\Omega$ series termination resistors (3-State)

## 74ABT162244 74ABTH162244

			LIMITS						
SYMBOL PARAMETER		TEST CONDITIONS			T <sub>amb</sub> = +25°C			T <sub>amb</sub> = -40°C to +85°C	
				Min	Тур	Max	Min	Max	1
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA			-0.9	-1.2		-1.2	V
		$V_{CC}$ = 4.5V; $I_{OH}$ = -3mA; $V_{I}$ = $V_{II}$	or V <sub>IH</sub>	2.5	2.9		2.5		V
V <sub>OH</sub>	V <sub>OH</sub> High-level output voltage <sup>3</sup>	$V_{CC} = 5V; I_{OH} = -3mA; V_I = V_{IL}$	or V <sub>IH</sub>	3.0	3.4		3.0		V
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} = V_{CC}$	′ <sub>IL</sub> or V <sub>IH</sub>	2.0	2.4		2.0		V
V <sub>OL</sub>	Low-level output voltage	$V_{CC}$ = 4.5V; $I_{OL}$ = 8mA; $V_I$ = $V_{IL}$	or V <sub>IH</sub>			0.65		0.65	V
VOL	Low-level output voltage	$V_{CC}$ = 4.5V; $I_{OL}$ = 12mA; $V_I$ = $V_{IL}$	or V <sub>IH</sub>			0.80		0.80	V
I	Input leakage current	$V_{CC}$ = 5.5V; $V_{I}$ = GND or 5.5V			±0.01	±1.0		±1.0	μΑ
	Input leakage current	$V_{CC}$ = 5.5V; $V_{I}$ = $V_{CC}$ or GND	Control pins	2)	±0.01	±1.0		±1.0	μA
I	74ABTH162244	$V_{CC} = 5.5V; V_I = V_{CC}$	Data pins	4	0.01	1.0		1.0	μΑ
		$V_{CC} = 5.5V; V_I = 0$		<u> </u>	-2.0	-3.0		-5.0	μΑ
	HOLD Bus Hold Current A Inputs <sup>4</sup> 74ABTH162244	$V_{CC} = 4.5V; V_I = 0.8V$	2	50			50		
I <sub>HOLD</sub>		$V_{CC} = 5.5V; V_1 = 2.0V$	-75			-75		μA	
		$V_{CC} = 5.5V; V_{I} = 0 \text{ to } 5.5V$		±500					$\vdash$
I <sub>OFF</sub>	Power-off leakage current	$V_{CC} = 0.0V; V_O \text{ or } V_I \le 4.5V$			±5.0	±100		±100	μΑ
I <sub>PU/PD</sub>	Power-up/down 3-State output current	$V_{CC} = 2.0V$ ; $V_{O} = 0.5V$ ; $V_{I} = GNI$ $V_{OE} = Don't care$	D or V <sub>CC</sub> ;		±5.0	±50		±50	μA
I <sub>OZH</sub>	3-State output High current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = V_{IL}$	or V <sub>IH</sub>		0.1	10		10	μΑ
I <sub>OZL</sub>	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.0V; V_{I} = V_{IL}$	or V <sub>IH</sub>		-0.1	-10		-10	μΑ
I <sub>CEX</sub>	Output High leakage current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GNI$	D or V <sub>CC</sub>		5.0	50		50	μΑ
Ι <sub>Ο</sub>	Output current <sup>1</sup>	$V_{CC} = 5.5V; V_{O} = 2.5V$		-50	-100	-180	-50	-180	mA
ICCH		$V_{CC}$ = 5.5V; Outputs High, $V_{I}$ = 0	GND or V <sub>CC</sub>		0.50	1.0		1.0	mA
I <sub>CCL</sub>	Quiescent supply current <sup>3</sup>	$V_{CC}$ = 5.5V; Outputs Low, $V_{I}$ = GND or $V_{CC}$			10	19		19	mA
I <sub>CCZ</sub>		$V_{CC}$ = 5.5V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>		0.50	1.0		1.0	mA	
	Additional supply current per input pin <sup>2, 3</sup>	Outputs enabled, one data input other inputs at $\rm V_{CC}$ or GND; $\rm V_{CC}$			100	250		250	μA
$\Delta I_{CC}$		Outputs disabled, one data input at 3.4V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = $5.5V$			100	250		250	μA
		Control pins, outputs disabled, one enable input at 3.4V, other inputs at V <sub>CC</sub> or GND; $V_{CC} = 5.5V$			100	250		250	μA

## **DC ELECTRICAL CHARACTERISTICS**

NOTES:

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
This is the increase in supply current for each input at 3.4V.
This data sheet limit may vary among suppliers.
This is the bus hold overdrive current required to force the input to the opposite logic state.

# 16-bit buffer/line driver with $30\Omega$ series termination resistors (3-State)

## 74ABT162244 74ABTH162244

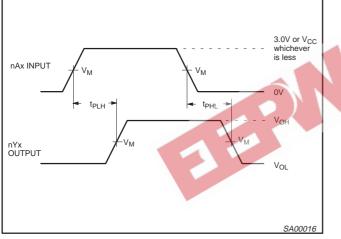
### **AC CHARACTERISTICS**

GND = 0V;  $t_R = t_F$  = 2.5ns;  $C_L$  = 50pF,  $R_L$  = 500 $\Omega$ 

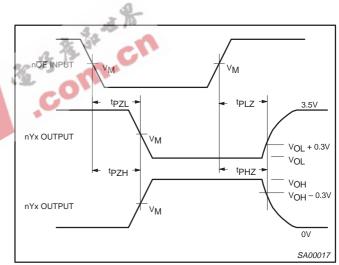
					LIMITS			
SYMBOL	PARAMETER	WAVEFORM		T <sub>amb</sub> = +25°C V <sub>CC</sub> = +5.0V	:	$T_{amb} = -40^{\circ}$ $V_{CC} = +5$	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Мах	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nAx to nYx	1	1.0 1.6	1.8 3.2	2.4 4.0	1.0 1.6	2.7 4.4	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to High and Low level	2	1.2 2.6	2.7 5.0	3.5 6.2	1.2 2.6	4.3 7.3	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from High and Low level	2	1.5 1.3	3.0 2.6	3.8 3.3	1.5 1.3	4.5 4.6	ns

### AC WAVEFORMS

 $V_{M}$  = 1.5V,  $V_{IN}$  = GND to 3.0V



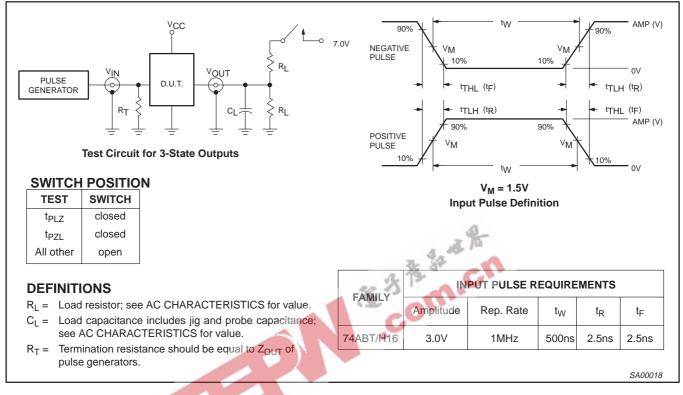
Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

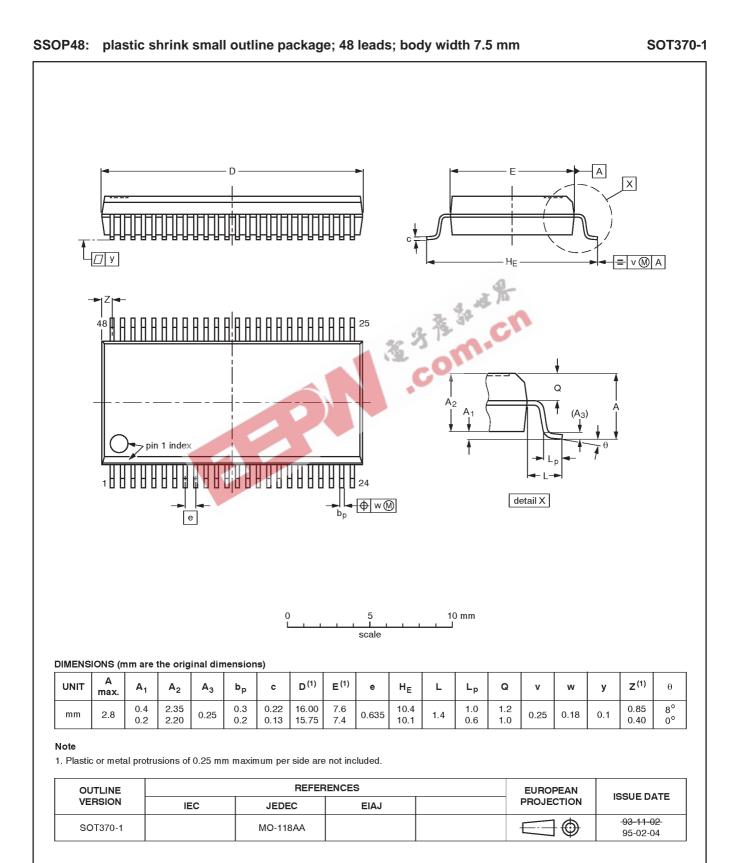
## 74ABT162244 74ABTH162244

### **TEST CIRCUIT AND WAVEFORMS**



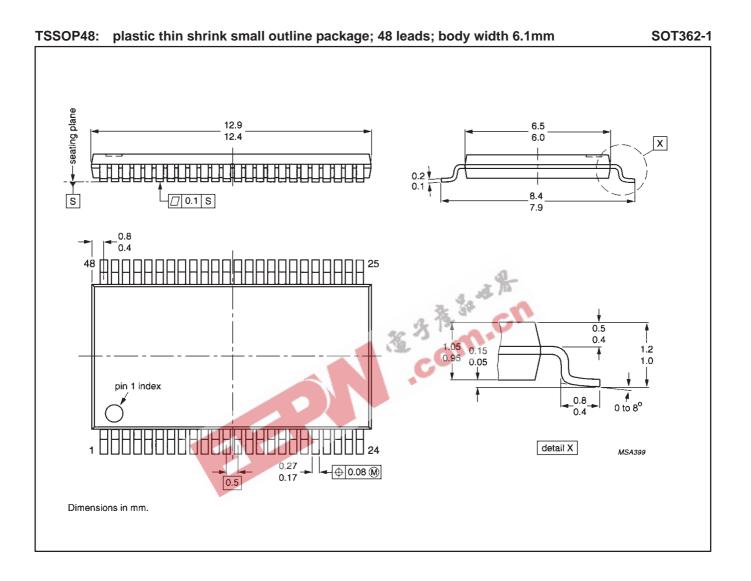
#### Product specification

74ABT162244 74ABTH162244



1998 Oct 22

## 74ABT162244 74ABTH162244



#### Product specification

## 74ABT162244 74ABTH162244

#### Data sheet status

Data sheet status	Product status	Definition <sup>[1]</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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